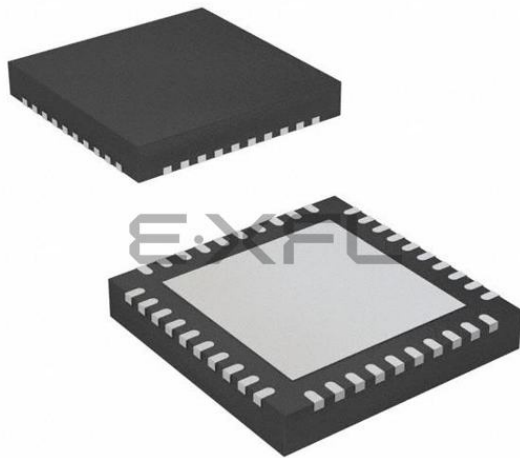




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Details

Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I ² S, POR, PWM, WDT
Number of I/O	27
Program Memory Size	200KB (200K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	40-VFQFN Exposed Pad
Supplier Device Package	PG-VQFN-40-17
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1403q040x0200aaxuma1

XMC1400 Data Sheet

Revision History: V1.3 2016-10

Previous Versions:

V1.2 2016-08

V1.1 2016-06

V1.0 2016-02

V0.3 2015-10

Page	Subjects
42 , 43	In Absolute Maximum Ratings renamed parameter V_{CM} to V_{INP2} , as the limitation is related to most P2 pins, also if no ACMP is available. Clarified limit to pins P2.[1,2,6:9,11] in Overload specification.
13	Corrected XMC1402-T038X0200 and XMC1402-Q048X0200 marking variants in Table 2
V1.2 2016-08	
many	Added XMC™ trademark
11 , 13 , 15	Added XMC1402-T038X0200, XMC1402-Q040X0200 and XMC1402-Q048X0200 marking variants
V1.1 2016-06	
many	Added TSSOP-38-9 package
11 , 13 , 15	Added XMC1402-T038 marking variants in TSSOP-38
11 , 13 , 15	Added XMC1403-Q040 marking variants
V1.0 2016-02	
10	The device provides four USIC channels.
11	XMC1401 devices available for max. ambient temperature of 85°C.
33	Reformatted pinout table.
58	Updated footnote to the definition of the start-up times of OSC_XTAL and RTC_XTAL oscillators.
73	Added Δf_{LT} parameter to on-chip oscillators DCO1 and DCO2.
85	Updated package outline drawings.

About this Document

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC1400 series devices.

The document describes the characteristics of a superset of the XMC1400 series devices. For simplicity, the various device types are referred to by the collective term XMC1400 throughout this document.

XMC1000 Family User Documentation

The set of user documentation includes:

- **Reference Manual**
 - describes the functionality of the superset of devices.
- **Data Sheets**
 - list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
 - list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.

Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to <http://www.infineon.com/xmc1000> to get access to the latest versions of those documents.

1.4 Chip Identification Number

The Chip Identification Number allows software to identify the marking. It is an 8 words value with the most significant 7 words stored in Flash configuration sector 0 (CS0) at address location : 1000 0F00_H (MSB) - 1000 0F1B_H (LSB). The least significant word and most significant word of the Chip Identification Number are the value of registers DBGROMID and IDCHIP, respectively.

Table 3 XMC1400 Chip Identification Number

Derivative	Value	Marking
XMC1401-Q048F0064	00014082 07CF00FF 1E071FF7 20006000 00000D00 00001000 00011000 10204083 _H	AA
XMC1401-Q048F0128	00014082 07CF00FF 1E071FF7 20006000 00000D00 00001000 00021000 10204083 _H	AA
XMC1401-F064F0064	000140A2 07CF00FF 1E071FF7 20006000 00000D00 00001000 00011000 10204083 _H	AA
XMC1401-F064F0128	000140A2 07CF00FF 1E071FF7 20006000 00000D00 00001000 00021000 10204083 _H	AA
XMC1402-T038X0032	00014013 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00009000 10204083 _H	AA
XMC1402-T038X0064	00014013 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00011000 10204083 _H	AA
XMC1402-T038X0128	00014013 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00021000 10204083 _H	AA
XMC1402-T038X0200	00014013 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00033000 10204083 _H	AA
XMC1402-Q040X0032	00014043 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00009000 10204083 _H	AA
XMC1402-Q040X0064	00014043 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00011000 10204083 _H	AA
XMC1402-Q040X0128	00014043 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00021000 10204083 _H	AA
XMC1402-Q040X0200	00014043 07FF00FF 1E071FF7 000F900F 00000D00 00001000 00033000 10204083 _H	AA
XMC1402-Q048X0032	00014083 07FF00FF 1E071FF7 100F900F 00000D00 00001000 00009000 10204083 _H	AA

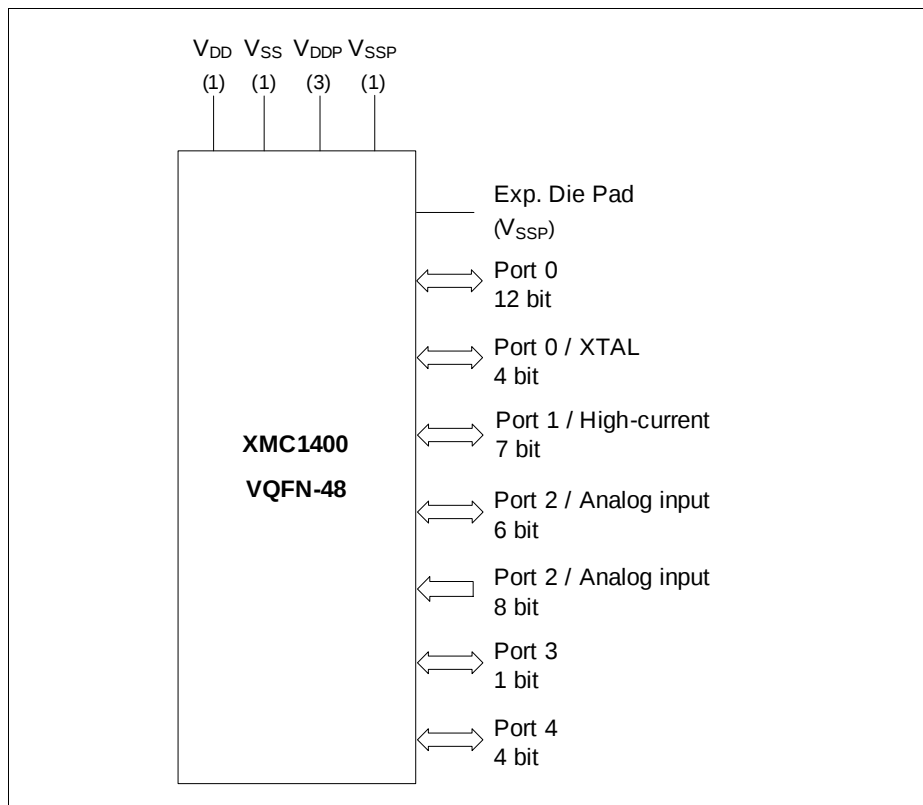


Figure 4 XMC1400 Logic Symbol for PG-VQFN-48-73

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs												
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P0.13	WWDT. SERVIC E_OUT	LEDTS1 .LINE5	LEDTS0 .COL2	LEDTS1 .COL2	CCU80. OUT32	USIC0. CH0.SE LO4	CCU80. OUT21		CAN.N1 _TXD				CCU80.I N3AB	CCU81.I N1AU	POSIF0. IN0B		USIC0 _CH0.D X2F				CAN.N1 _RXDB	
P0.14	BCCU0. OUT7	LEDTS1 .LINE6	LEDTS0 .COL1	LEDTS1 .COL1	CCU80. OUT31	USIC0 _CH0.DO UTO	USIC0 _CH0.SC LKOUT		CAN.N0 _TXD					CCU81.I N2AU	POSIF0. IN1B	USIC0 _CH0.DX 0A	USIC0 _CH0.D X1A	USIC1 _CH1.DX 5B			CAN.N0 _RXDC	
P0.15	BCCU0. OUT8	LEDTS1 .LINE7	LEDTS0 .COL0	LEDTS1 .COL0	CCU80. OUT30	USIC0 _CH1.MC LKOUT			CAN.N0 _TXD					CCU81.I N3AU	POSIF0. IN2B	USIC0 _CH0.DX 0B		USIC1 _CH1.DX 3B	USIC1 _CH1.DX 4B		CAN.N0 _RXDD	
P1.0	BCCU0. OUT0	CCU40. OUT0	LEDTS0 .COL0	LEDTS1 .COLA	CCU80. OUT00	ACMP1. OUT	USIC0 _CH0.DO UTO	CCU81. OUT00	CAN.N0 _TXD						POSIF0. IN2A	USIC0 _CH0.DX 0C					CAN.N0 _RXDG	
P1.1	ERU1.P DOUT1	CCU40. OUT1	LEDTS0 .COL1	LEDTS1 .COL0	CCU80. OUT01	USIC0 _CH0.DO UTO	USIC0 _CH1.SE LO0	CCU81. OUT01	CAN.N0 _TXD						POSIF0. IN1A	USIC0 _CH0.DX 0D	USIC0 _CH0.D X1D		USIC0 _CH1.DX 2E		CAN.N0 _RXDH	
P1.2	ERU1.P DOUT2	CCU40. OUT2	LEDTS0 .COL2	LEDTS1 .COL1	CCU80. OUT10	ACMP2. OUT	USIC0 _CH1.DO UTO	CCU81. OUT10	CAN.N1 _TXD						POSIF0. IN0A			USIC0 _CH1.DX 0B			CAN.N1 _RXDG	
P1.3	ERU1.P DOUT3	CCU40. OUT3	LEDTS0 .COL3	LEDTS1 .COL2	CCU80. OUT11	USIC0 _CH1.SC LKOUT	USIC0 _CH1.DO UTO	CCU81. OUT11	CAN.N1 _TXD									USIC0 _CH1.DX 0A	USIC0 _CH1.DX 1A		CAN.N1 _RXDH	
P1.4	ERU1.P DOUT0	USIC0 _CH1.SC LKOUT	LEDTS0 .COL4	LEDTS1 .COL3	CCU80. OUT20	USIC0 _CH0.SE LO0	USIC0 _CH1.SE LO1	CCU81. OUT20	CCU41. OUT0							USIC0 _CH0.DX 5E		USIC0 _CH1.DX 5E				
P1.5	ERU1.P DOUT1	USIC0 _CH0.DO UTO	LEDTS0 .COLA	BCCU0. OUT1	CCU80. OUT21	USIC0 _CH0.SE LO1	USIC0 _CH1.SE LO2	CCU81. OUT21	CCU41. OUT1									USIC0 _CH1.DX 5F				
P1.6	ERU1.P DOUT2	USIC0 _CH1.DO UTO	LEDTS0 .COL5	USIC0 _CH0.SC LKOUT	BCCU0. OUT2	USIC0 _CH0.SE LO2	USIC0 _CH1.SE LO3	CCU81. OUT30	CCU41. OUT2						POSIF1. IN2A	USIC0 _CH0.DX 5F						
P1.7	BCCU0. OUT8	CCU40. OUT3	LEDTS0 .COL6	LEDTS1 .COL4		ACMP3. OUT	ERU1.P DOUT3	CCU81. OUT31	CCU41. OUT3						POSIF1. IN1A	USIC1 _CH0.DX 5B			USIC1 _CH1.DX 2C			
P1.8	BCCU0. OUT0	CCU40. OUT0	USIC1 _CH1.SC LKOUT	VADC0. EMUX02		ACMP1. OUT	ERU1.P DOUT0	CCU81. OUT32							POSIF1. IN0A	USIC1 _CH0.DX 3B	USIC1 _CH0.D X4B		USIC1 _CH1.DX 1C			
P2.0	ERU0.P DOUT3	CCU40. OUT0	ERU0.G OUT3	LEDTS1 .COL5	CCU80. OUT20	USIC0 _CH0.DO UTO	USIC0 _CH0.SC LKOUT	CCU81. OUT20	CAN.N0 _TXD		VADC0. G0CH5					USIC0 _CH0.DX 0E	USIC0 _CH0.D X1E		USIC0 _CH1.DX 2F		CAN.N0 _RXDE	ERU0.0 B0
P2.1	ERU0.P DOUT2	CCU40. OUT1	ERU0.G OUT2	LEDTS1 .COL6	CCU80. OUT21	USIC0 _CH0.DO UTO	USIC0 _CH1.SC LKOUT	CCU81. OUT21	CAN.N0 _TXD	ACMP2.I NP	VADC0. G0CH6					USIC0 _CH0.DX 0F		USIC0 _CH1.DX 3A	USIC0 _CH1.DX 4A		CAN.N0 _RXDF	ERU0.1 B0

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs											
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P4.10		LEDTS2 .LINE6	LEDTS2 .COL1	LEDTS1 .COL1	CCU80. OUT00	CCU40. OUT2	USIC1_ CH0.SE LO3	CCU81. OUT32	CCU81. OUT00	BCCU0. TRAPIN D	CCU40.I N2AV	CCU41.I N2BA		CCU81.I N3AB			USIC1_ CH0.D X2D	USIC1_ CH1.DX 5A			
P4.11		LEDTS2 .LINE7	LEDTS2 .COL0	LEDTS1 .COL0	CCU80. OUT01	CCU40. OUT3	USIC1_ CH0.SE LO4	CCU81. OUT33	CCU81. OUT01		CCU40.I N3AV	CCU41.I N3BA					USIC1_ CH0.D X2E	USIC1_ CH1.DX 3A	USIC1_ CH1.DX 4A		

3 Electrical Parameter

This section provides the electrical parameter which are implementation-specific for the XMC1400.

3.1 General Parameters

3.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XMC1400 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

- **CC**
Such parameters indicate **C**ontroller **C**haracteristics, which are distinctive feature of the XMC1400 and must be regarded for a system design.
- **SR**
Such parameters indicate **S**ystem **R**equirements, which must be provided by the application system in which the XMC1400 is designed in.

3.1.2 Absolute Maximum Ratings

Stresses above the values listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Table 11 Absolute Maximum Rating Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min	Typ.	Max.		
Junction temperature	T_J	SR	-40	–	115	°C	–
Storage temperature	T_{ST}	SR	-40	–	125	°C	–
Voltage on power supply pin with respect to V_{SSP}	V_{DDP}	SR	-0.3	–	6	V	–
Voltage on digital pins with respect to V_{SSP} ¹⁾	V_{IN}	SR	-0.5	–	$V_{DDP} + 0.5$ or max. 6	V	whichever is lower
Voltage on P2 pins with respect to V_{SSP} ²⁾	V_{INP2}	SR	-0.3	–	$V_{DDP} + 0.3$	V	–
Voltage on analog input pins with respect to V_{SSP}	V_{AIN} V_{AREF}	SR	-0.5	–	$V_{DDP} + 0.5$ or max. 6	V	whichever is lower
Input current on any pin during overload condition	I_{IN}	SR	-10	–	10	mA	–
Absolute maximum sum of all input currents during overload condition	ΣI_{IN}	SR	-50	–	+50	mA	–

1) Excluding port pins P2.[1,2,6,7,8,9,11].

2) Applicable to port pins P2.[1,2,6,7,8,9,11].

3.2.2 Analog to Digital Converters (ADC)

Table 17 shows the Analog to Digital Converter (ADC) characteristics.

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 17 ADC Characteristics (Operating Conditions apply)¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage range (internal reference)	V_{DD_int} SR	2.0	–	3.0	V	SHSCFG.AREF = 11 _B ; CALCTR.CALGNSTC = 0C _H for f_{SH} = 32 MHz, 12 _H for f_{SH} = 48 MHz
		3.0	–	5.5	V	SHSCFG.AREF = 10 _B
Supply voltage range (external reference)	V_{DD_ext} SR	3.0	–	5.5	V	SHSCFG.AREF = 00 _B
Analog input voltage range	V_{AIN} SR	V_{SSP} - 0.05	–	V_{DDP} + 0.05	V	
Auxiliary analog reference ground ²⁾	V_{REFGND} SR	V_{SSP} - 0.05	–	1.0	V	G0CH0
		V_{SSP} - 0.05	–	0.2	V	G1CH0
Internal reference voltage (full scale value)	V_{REFINT} CC	5			V	
Switched capacitance of an analog input	C_{AINS} CC	–	1.2	2	pF	GNCTRxz.GAINy = 00 _B (unity gain)
		–	1.2	2	pF	GNCTRxz.GAINy = 01 _B (gain g1)
		–	4.5	6	pF	GNCTRxz.GAINy = 10 _B (gain g2)
		–	4.5	6	pF	GNCTRxz.GAINy = 11 _B (gain g3)
Total capacitance of an analog input	C_{AINT} CC	–	–	10	pF	
Total capacitance of the reference input	C_{AREFT} CC	–	–	10	pF	

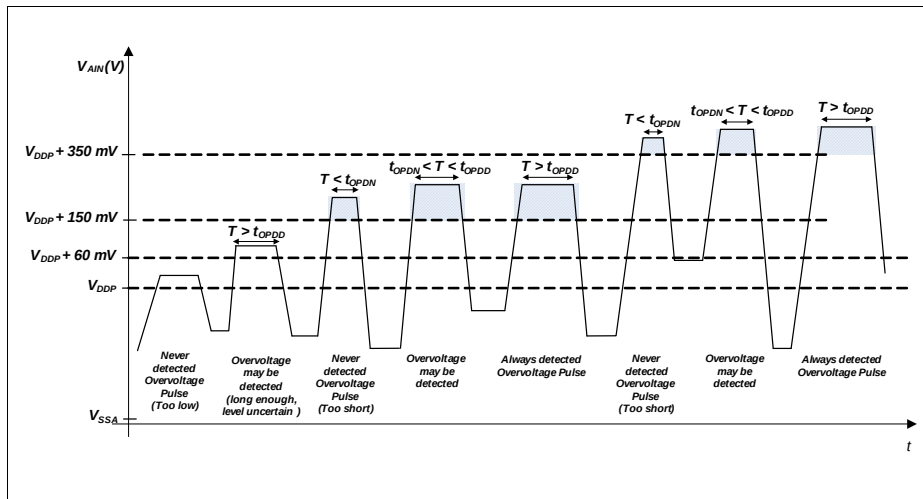


Figure 14 ORC Detection Ranges

3.2.6 Oscillator Pins

Note: It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimal parameters for the oscillator operation. Please refer to the limits specified by the crystal or ceramic resonator supplier.

Note: These parameters are not subject to production test, but verified by design and/or characterization.

The oscillator pins can be operated with an external crystal/resonator (see [Figure 15](#)) or in direct input mode (see [Figure 16](#)).

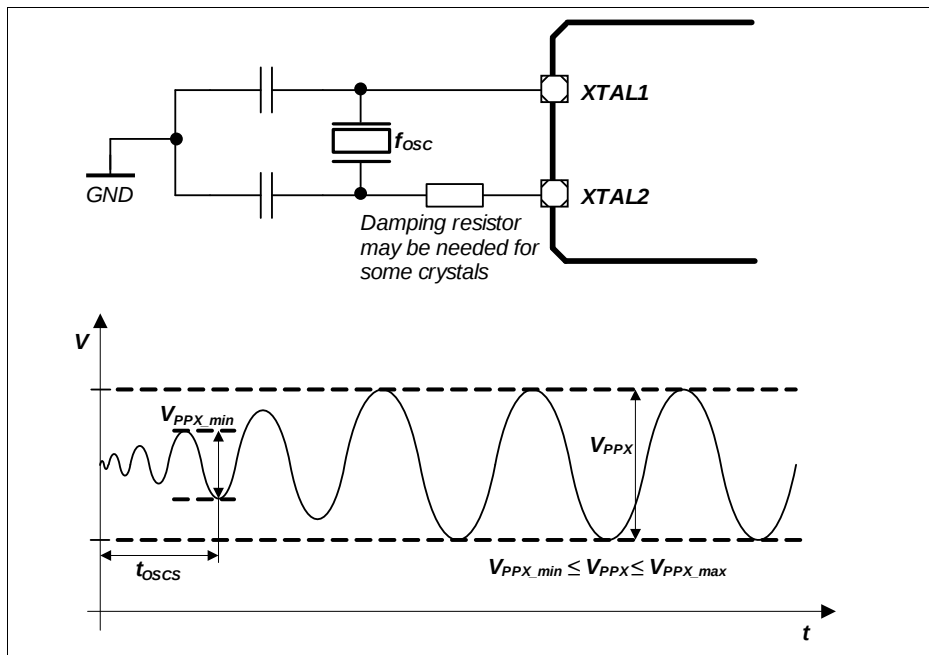


Figure 15 Oscillator in Crystal Mode

Figure 17 shows typical graphs for active mode supply current for $V_{DDP} = 5\text{ V}$, $V_{DDP} = 3.3\text{ V}$, $V_{DDP} = 1.8\text{ V}$ across different clock frequencies.

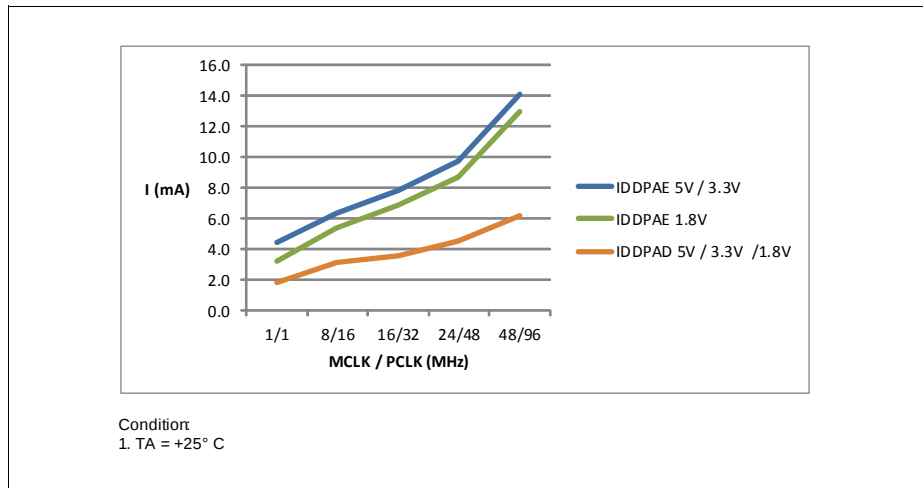


Figure 17 Active mode, a) peripherals clocks enabled, b) peripherals clocks disabled: Supply current I_{DDPA} over supply voltage V_{DDP} for different clock frequencies

Figure 18 shows typical graphs for sleep mode current for $V_{DDP} = 5\text{ V}$, $V_{DDP} = 3.3\text{ V}$, $V_{DDP} = 1.8\text{ V}$ across different clock frequencies.

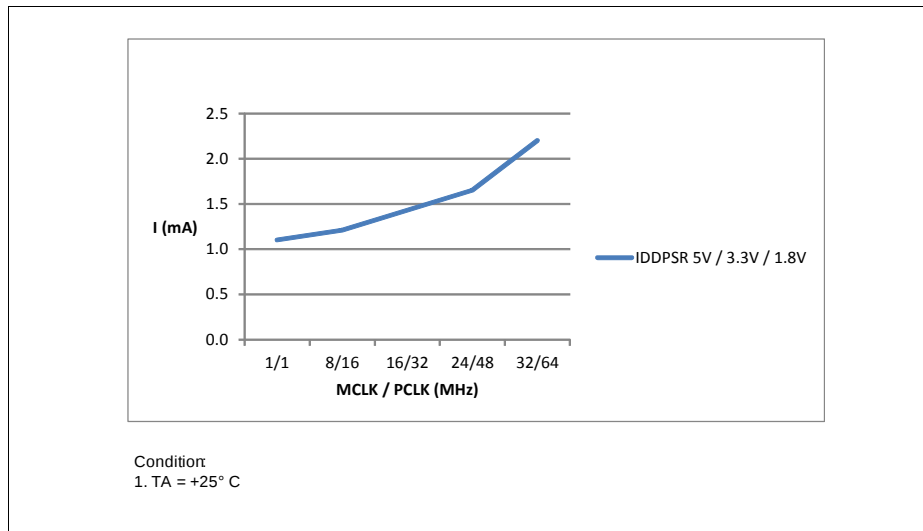


Figure 18 Sleep mode, peripherals clocks disabled, Flash powered down:
Supply current I_{DDPSD} over supply voltage V_{DDP} for different clock frequencies

Table 24 provides the active current consumption of some modules operating at 5 V power supply at 25 °C. The typical values shown are used as a reference guide on the current consumption when these modules are enabled.

Table 24 Typical Active Current parameter table

Active Current Consumption	Symbol	Limit Values	Unit	Test Condition
		Typ.		
Baseload current	I_{CPUDDC}	4.14	mA	Modules including Core, SCU, PORT, memories, ANATOP ¹⁾
VADC and SHS	I_{ADCDDC}	3.73	mA	Set CGATCLR0.VADC to 1 ²⁾
USICx	$I_{USIC0DDC}$	1.35	mA	Set CGATCLR0.USIC0 to 1 ³⁾
CCU4x	$I_{CCU40DDC}$	0.99	mA	Set CGATCLR0.CCU40 to 1 ⁴⁾
CCU8x	$I_{CCU80DDC}$	1.00	mA	Set CGATCLR0.CCU80 to 1 ⁵⁾
POSIFx	$I_{PIF0DDC}$	1.05	mA	Set CGATCLR0.POSIF0 to 1 ⁶⁾
LEDTSx	$I_{LTSxDDC}$	1.14	mA	Set CGATCLR0.LEDTSx to 1 ⁷⁾
BCCU0	$I_{BCCU0DDC}$	0.29	mA	Set CGATCLR0.BCCU0 to 1 ⁸⁾
MATH	$I_{MATHDDC}$	0.50	mA	Set CGATCLR0.MATH to 1 ⁹⁾
WDT	I_{WDTDDC}	0.03	mA	Set CGATCLR0.WDT to 1 ¹⁰⁾
RTC	I_{RTCDDC}	0.01	mA	Set CGATCLR0.RTC to 1 ¹¹⁾
MultiCAN	$I_{MCANDDC}$	1.38	mA	Set CGATCLR0.MCAN0 to 1 ¹²⁾

1) Baseload current is measured with device running in user mode, MCLK=PCLK=48 MHz, with an endless loop in the flash memory. The clock to the modules stated in CGATSTAT0 are gated.

2) Active current is measured with: module enabled, MCLK=48 MHz, running in auto-scan conversion mode

3) Active current is measured with: module enabled, each of the 2 USIC channels sending alternate messages at 57.6 kbaud every 200 ms

4) Active current is measured with: module enabled, MCLK=PCLK=48 MHz, 1 CCU4 slice for PWM switching at 20kHz with duty cycle varying at 10%-90%, 1 CCU4 slice in capture mode for reading period and duty cycle

5) Active current is measured with: module enabled, MCLK=PCLK=48 MHz, 3 CCU8 slices with PWM frequency at 20kHz and a period match interrupt used to toggle duty cycle between 10% and 90%

6) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96 MHz, hall sensor mode

7) Active current is measured with: module enabled, MCLK=48 MHz, 1 LED column, 6 LED/TS lines, Pad Scheme A with large pad hysteresis config, time slice duration = 1.048 ms

8) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96MHz, FCLK=0.8 MHz, Normal mode (BCCU clock = FCLK/4), 4 BCCU Channels with packers enabled and 1 Dimming Engine, change color or dim every 1s

9) Active current is measured with: module enabled, MCLK=48 MHz, PCLK=96 MHz, tangent calculation in while loop; CORDIC circular rotation, no keep, autostart; 32-by-32 bit signed DIV, autostart, DVS right shift by 11

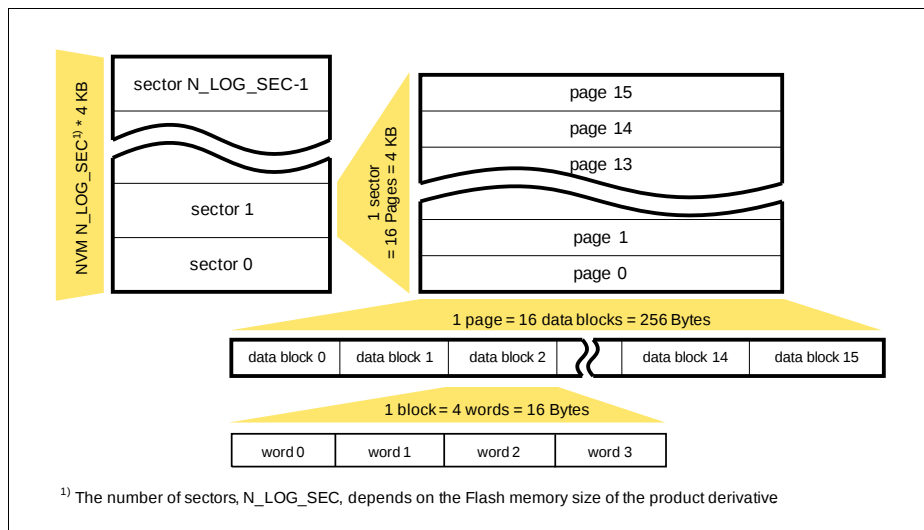


Figure 19 Logical Structure of the Flash

3.3.6 Peripheral Timings

Note: These parameters are not subject to production test, but verified by design and/or characterization.

3.3.6.1 Synchronous Serial Interface (USIC SSC) Timing

The following parameters are applicable for a USIC channel operated in SSC mode.

Note: Operating Conditions apply.

Table 31 USIC SSC Master Mode Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKOUT master clock period	t_{CLK} CC	$4/MCLK$	–	–	ns	
Slave select output SELO active to first SCLKOUT transmit edge	t_1 CC	$t_{CLK}/2 - 28$	–	–	ns	
Slave select output SELO inactive after last SCLKOUT receive edge	t_2 CC	0	–	–	ns	
Data output DOUT[3:0] valid time	t_3 CC	-28	–	28	ns	
Receive data input DX0/DX[5:3] setup time to SCLKOUT receive edge	t_4 SR	75	–	–	ns	
Data input DX0/DX[5:3] hold time from SCLKOUT receive edge	t_5 SR	0	–	–	ns	

Table 32 USIC SSC Slave Mode Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
DX1 slave clock period	t_{CLK} SR	$4/MCLK$	–	–	ns	
Select input DX2 setup to first clock input DX1 transmit edge ¹⁾	t_{10} SR	16	–	–	ns	

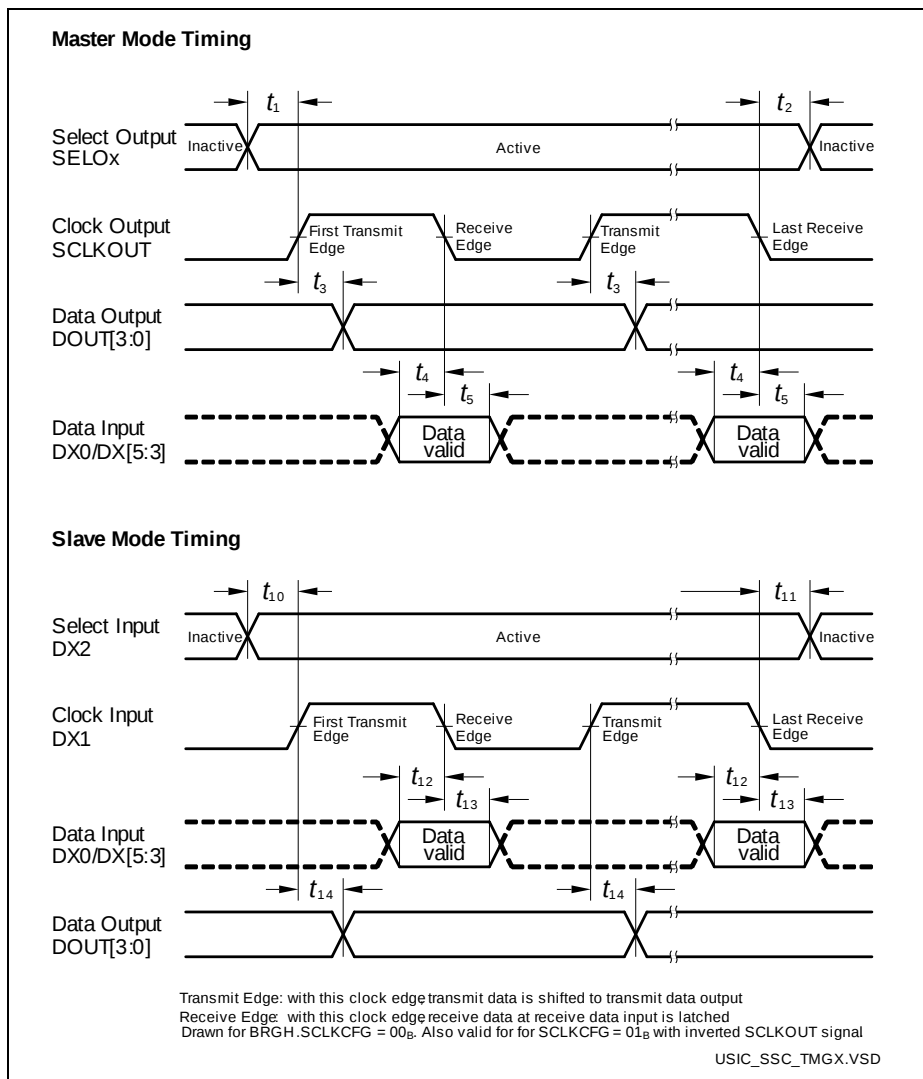


Figure 25 USIC - SSC Master/Slave Mode Timing

Note: This timing diagram shows a standard configuration, for which the slave select signal is low-active, and the serial clock signal is not shifted and not inverted.

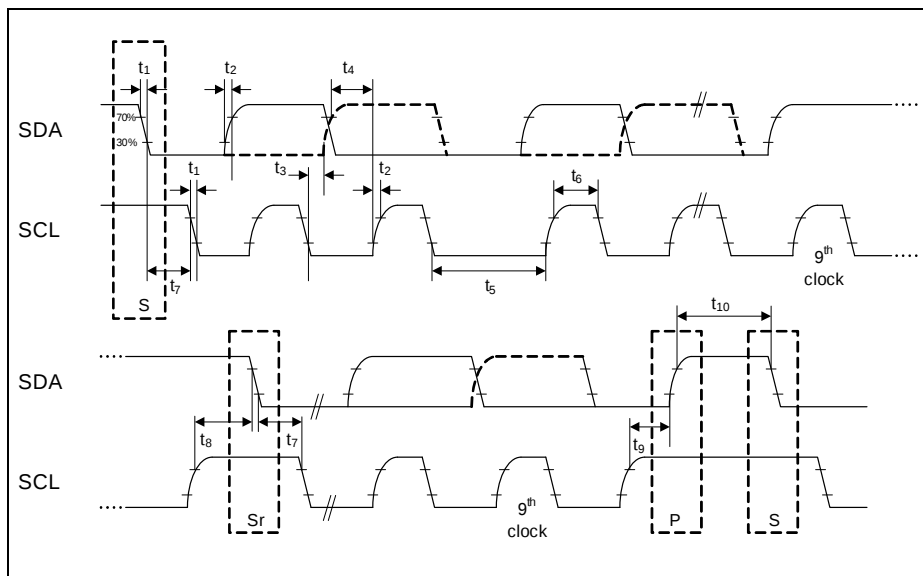


Figure 26 USIC IIC Timing

3.3.6.3 Inter-IC Sound (IIS) Interface Timing

The following parameters are applicable for a USIC channel operated in IIS mode.

Note: Operating Conditions apply.

Table 35 USIC IIS Master Transmitter Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_1 CC	$4/f_{MCLK}$	-	-	ns	
Clock HIGH	t_2 CC	$0.35 \times t_{1min}$	-	-	ns	
Clock Low	t_3 CC	$0.35 \times t_{1min}$	-	-	ns	
Hold time	t_4 CC	0	-	-	ns	
Clock rise time	t_5 CC	-	-	$0.15 \times t_{1min}$	ns	

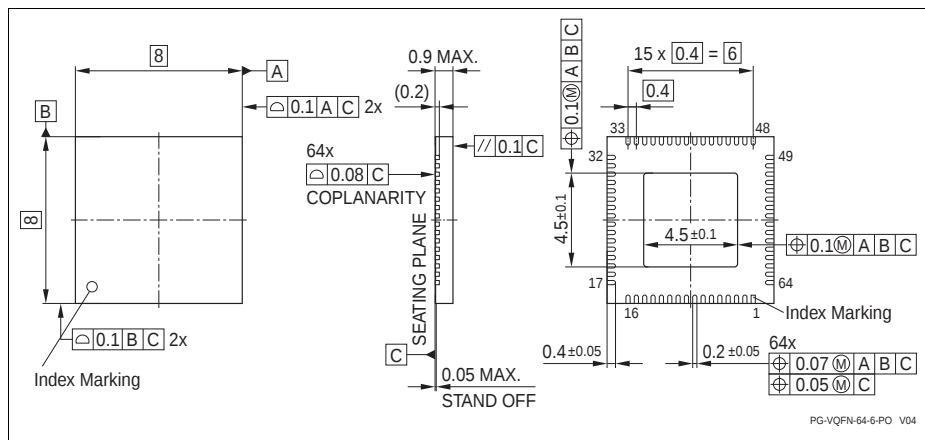


Figure 33 PG-VQFN-64-6

All dimensions in mm.

5 Quality Declaration

Table 38 shows the characteristics of the quality parameters in the XMC1400.

Table 38 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM} SR	-	2000	V	Conforming to EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM} SR	-	500	V	Conforming to JESD22-C101-C
Moisture sensitivity level	MSL CC	-	3	-	JEDEC J-STD-020D
Soldering temperature	T_{SDR} SR	-	260	°C	Profile according to JEDEC J-STD-020D

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